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Designed for: Public Release		Mod. Date: 2013-6-25	
Project Title: Change in menu Project\Project Options\Parameter			
Number: XX###	Rev: E1	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 1 of 1
Drawn By:	File: PWM Filter.SchDoc	Size: B	http://www.ti.com
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	?Texas Instruments 2012	

1 2 3 4 5 6

A

A

H1
NY PMS 440 0025 PH

H2
NY PMS 440 0025 PH

PCB
LOGO
Texas Instruments

H3
NY PMS 440 0025 PH

H4
NY PMS 440 0025 PH

B

B

C

C

D

D

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Designed for: Public Release	Mod. Date: 2013-5-21
Project Title: Change in menu Project\Project Options\Parameter	
Number: XX###	Rev: E1
SVN Rev: Not in version control	Sheet Title:
Assembly Variant: [No Variations]	Sheet: 1 of 1
File: Hardware_ANSI-B_SchDoc	Size: B
Engineer: Enter name of project lead	Contact: http://www.ti.com/support



1 2 3 4 5 6

The Stackup Legend below this is static. If you change the stackup, update the Legend.

Layer Stack Up Detail for: Ref_Design.PcbDoc			
Layer Name	Color	Dielectric Thickness	Generic Part ID
Top Solder Mask	C:GTS		Solder Resist
Top Layer	C:GTL	1.4mil	FR-4
Bottom Layer	C:GBL	1.4mil	
Bottom Solder Mask	C:GBS		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
3450MIL X 4950MIL

Number of Layers : 2
 MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 8 MIL
 MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

FR-4 FR-4 High Tg OTHER _____

THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

COPPER THICKNESS (FINISHED):
 OUTER: 1.4MIL (1oz) 2MIL (1.4oz) 2.8MIL (2oz)
 INNER SIGNAL: 1.4MIL (1oz) 2.8MIL (2oz)

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENG) Pb-FREE HASL
 OTHER _____

ARRAY/PANEL:
 CUT AND TRM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S D/LOGO: RAL METAL SLK



PROJECT TITLE:
 Change in menu Project\Project Options\Parameters

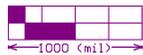
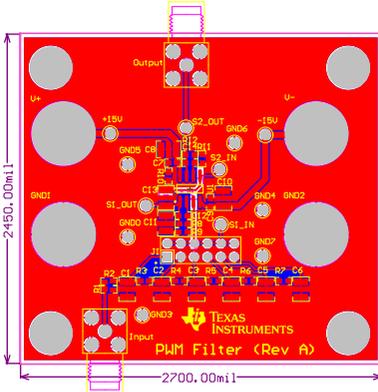
DESIGNED FOR:
 Public Release

FILE NAME:
 PWM Filter.PcbDoc

ENGINEER:
 Enter name of project: Whaddid the Layout?

LAYOUT BY:
 ALTIM DESIGNER VERSION:
 10.0.0.27009

SCALE: 1.00



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M9 Title Sheet

Comment	Designator	Footprint	LibRef	Quantity
5000	+15V, -15V, S1_IN, S1_OUT, S2_IN, S2_OUT	Keystone5000	5000	6
470n	C1	1210	Capacitor	1
47n	C2	1210	Capacitor	1
4.7n	C3	1210	Capacitor	1
470p	C4	1210	Capacitor	1
NU	C5, C6	1210	Capacitor	2
0.1u	C7, C9	0603	Capacitor	2
10u	C8, C10	1210	Capacitor	2
100u	C11, C13	1210	Capacitor	2
1p	C12	0603	Capacitor	1
10p	C14	0603	Capacitor	1
5001	GNDU, GND3, GND4, GND5, GND6, GND7	Keystone5001	5001	6
108-0740-001	GND1, GND2, V+, V-	Johnson_108-0740-001	108-0740-001	4
NY PMS 440 0025 PH	H1, H2, H3, H4	NY PMS 440 0025 PH	NY PMS 440 0025 PH	4
901-143	Input, Output	Amphenol_901-143	901-143	2
TSW-106-07-G-D	J1	TSW-106-07-G-D	TSW-106-07-G-D	1
50	R1	0603	Resistor	1
866	R2	0603	Resistor	1
8.66k	R3	0603	Resistor	1
86.6k	R4	0603	Resistor	1
866k	R5	0603	Resistor	1
NU	R6, R7	0603	Resistor	2
310k	R8	0603	Resistor	1
10k	R9, R10	0603	Resistor	2
1k	R11	0603	Resistor	1
31k	R12	0603	Resistor	1
OPA2209	U1	D0008A_M	OPA2188	1

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